BAS40 series; 1PSxxSB4x series

General-purpose Schottky diodes

Rev. 08 — 13 January 2010 Product data sheet

1. Product profile

1.1 General description

General-purpose Schottky diodes in small Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
1PS70SB40	SOT323	SC-70	single diode
1PS76SB40	SOD323	SC-76	single diode
1PS79SB40	SOD523	SC-79	single diode
BAS40	SOT23	-	single diode
BAS40H	SOD123F	-	single diode
BAS40L	SOD882	-	single diode
BAS40W	SOT323	SC-70	single diode
1PS70SB44	SOT323	SC-70	dual series
BAS40-04	SOT23	-	dual series
BAS40-04W	SOT323	SC-70	dual series
1PS70SB45	SOT323	SC-70	dual common cathode
1PS75SB45	SOT416	SC-75	dual common cathode
BAS40-05	SOT23	-	dual common cathode
BAS40-05W	SOT323	SC-70	dual common cathode
1PS70SB46	SOT323	SC-70	dual common anode
BAS40-06	SOT23	-	dual common anode
BAS40-06W	SOT323	SC-70	dual common anode
BAS40-07	SOT143B	-	dual isolated
BAS40-07V	SOT666	-	dual isolated
BAS40-05V	SOT666	-	quadruple common cathode/ common cathode
1PS88SB48	SOT363	SC-88	quadruple common cathode/ common cathode
BAS40XY	SOT363	SC-88	quadruple; 2 series

NXP founded by Philips

1.2 Features

- High switching speed
- High breakdown voltage
- Low leakage current
- Low capacitance

1.3 Applications

- Ultra high-speed switching
- Voltage clamping

1.4 Quick reference data

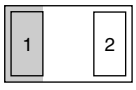
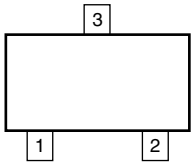
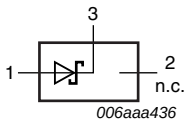
Table 2. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
I_F	forward current			-	-	120	mA
V_F	forward voltage	I_F = 1 mA	[1]	-	-	380	mV
V_R	reverse voltage			-	-	40	V

[1] Pulse test: $t_p \leq 300\ \mu s$; $\delta \leq 0.02$.

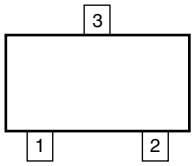
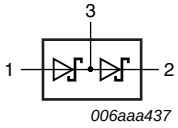
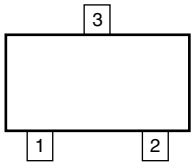
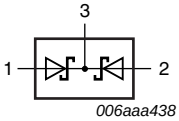
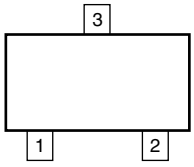
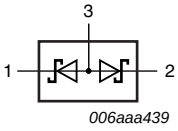
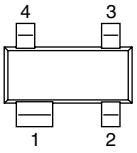
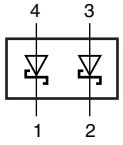
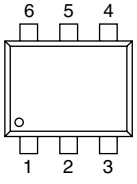
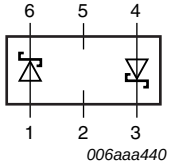
2. Pinning information

Table 3. Pinning

Pin	Description		Simplified outline	Symbol
BAS40H; 1PS76SB40; 1PS79SB40				
1	cathode	[1]	 001aab540	 sym001
2	anode			
BAS40L				
1	cathode	[1]	 Transparent top view	 sym001
2	anode			
BAS40; BAS40W; 1PS70SB40				
1	anode		 006aaa144	 006aaa436
2	not connected			
3	cathode			

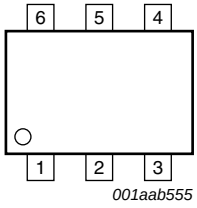
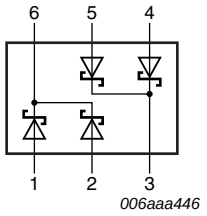
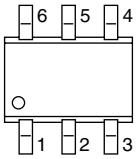
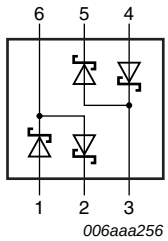
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Table 3. Pinning *...continued*

Pin	Description	Simplified outline	Symbol
BAS40-04; BAS40-04W; 1PS70SB44			
1	anode (diode 1)	 006aaa144	 006aaa437
2	cathode (diode 2)		
3	cathode (diode 1), anode (diode 2)		
BAS40-05; BAS40-05W; 1PS70SB45; 1PS75SB45			
1	anode (diode 1)	 006aaa144	 006aaa438
2	anode (diode 2)		
3	cathode (diode 1), cathode (diode 2)		
BAS40-06; BAS40-06W; 1PS70SB46			
1	cathode (diode 1)	 006aaa144	 006aaa439
2	cathode (diode 2)		
3	anode (diode 1), anode (diode 2)		
BAS40-07			
1	cathode (diode 1)		 006aaa434
2	cathode (diode 2)		
3	anode (diode 2)		
4	anode (diode 1)		
BAS40-07V			
1	anode (diode 1)		 006aaa440
2	not connected		
3	cathode (diode 2)		
4	anode (diode 2)		
5	not connected		
6	cathode (diode 1)		

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Table 3. Pinning *...continued*

Pin	Description	Simplified outline	Symbol
BAS40-05V; 1PS88SB48			
1	anode (diode 1)	 001aab555	 006aaa446
2	anode (diode 2)		
3	cathode (diode 3), cathode (diode 4)		
4	anode (diode 3)		
5	anode (diode 4)		
6	cathode (diode 1), cathode (diode 2)		
BAS40XY			
1	anode (diode 1)		 006aaa256
2	cathode (diode 2)		
3	anode (diode 3), cathode (diode 4)		
4	anode (diode 4)		
5	cathode (diode 3)		
6	cathode (diode 1), anode (diode 2)		

[1] The marking bar indicates the cathode.

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3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
1PS70SB40	SC-70	plastic surface-mounted package; 3 leads	SOT323
1PS76SB40	SC-76	plastic surface-mounted package; 2 leads	SOD323
1PS79SB40	SC-79	plastic surface-mounted package; 2 leads	SOD523
BAS40	-	plastic surface-mounted package; 3 leads	SOT23
BAS40H	-	plastic surface-mounted package; 2 leads	SOD123F
BAS40L	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm	SOD882
BAS40W	SC-70	plastic surface-mounted package; 3 leads	SOT323
1PS70SB44	SC-70	plastic surface-mounted package; 3 leads	SOT323
BAS40-04	-	plastic surface-mounted package; 3 leads	SOT23
BAS40-04W	SC-70	plastic surface-mounted package; 3 leads	SOT323
1PS70SB45	SC-70	plastic surface-mounted package; 3 leads	SOT323
1PS75SB45	SC-75	plastic surface-mounted package; 3 leads	SOT416
BAS40-05	-	plastic surface-mounted package; 3 leads	SOT23
BAS40-05W	SC-70	plastic surface-mounted package; 3 leads	SOT323
1PS70SB46	SC-70	plastic surface-mounted package; 3 leads	SOT323
BAS40-06	-	plastic surface-mounted package; 3 leads	SOT23
BAS40-06W	SC-70	plastic surface-mounted package; 3 leads	SOT323
BAS40-07	-	plastic surface-mounted package; 4 leads	SOT143B
BAS40-07V	-	plastic surface-mounted package; 6 leads	SOT666
BAS40-05V	-	plastic surface-mounted package; 6 leads	SOT666
1PS88SB48	SC-88	plastic surface-mounted package; 6 leads	SOT363
BAS40XY	SC-88	plastic surface-mounted package; 6 leads	SOT363

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4. Marking

Table 5. Marking codes

Type number	Marking code[1]	Type number	Marking code[1]
1PS70SB40	6*3	1PS75SB45	45
1PS76SB40	S4	BAS40-05	45*
1PS79SB40	T	BAS40-05W	65*
BAS40	43*	1PS70SB46	6*6
BAS40H	AJ	BAS40-06	46*
BAS40L	S6	BAS40-06W	66*
BAS40W	63*	BAS40-07	47*
1PS70SB44	6*4	BAS40-07V	67
BAS40-04	44*	BAS40-05V	65
BAS40-04W	64*	1PS88SB48	8*5
1PS70SB45	6*5	BAS40XY	40*

[1] * = -: made in Hong Kong
* = p: made in Hong Kong
* = t: made in Malaysia
* = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode						
V_R	reverse voltage			-	40	V
I_F	forward current			-	120	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$		-	120	mA
I_{FSM}	non-repetitive peak forward current	$t_p \leq 10$ ms	[1]	-	200	mA
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			−65	+150	°C
T_{stg}	storage temperature			−65	+150	°C

[1] T_j = 25 °C prior to surge.

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6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per device							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]				
	SOT23			-	-	500	K/W
	SOT143B			-	-	500	K/W
	SOT363 (1PS88SB48)			-	-	416	K/W
	SOT416			-	-	833	K/W
	SOT666 (BAS40-05V)		[2]	-	-	225	K/W
	SOT666 (BAS40-07V)		[2]	-	-	416	K/W
	SOD123F		[2]	-	-	330	K/W
	SOD323			-	-	450	K/W
	SOD523		[2]	-	-	450	K/W
	SOD882		[2]	-	-	500	K/W
	SOT323			-	-	625	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point						
	SOT363 (BAS40XY)		[3]	-	-	260	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Soldering point at pins 2, 3, 5 and 6.

7. Characteristics

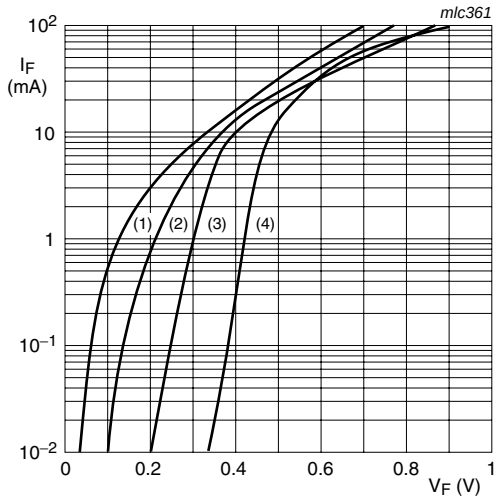
Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
V_F	forward voltage		[1]				
		I_F = 1 mA		-	-	380	mV
		I_F = 10 mA		-	-	500	mV
		I_F = 40 mA		-	-	1	V
I_R	reverse current	V_R = 30 V		-	-	1	µA
		V_R = 40 V		-	-	10	µA
C_d	diode capacitance	V_R = 0 V; f = 1 MHz		-	-	5	pF

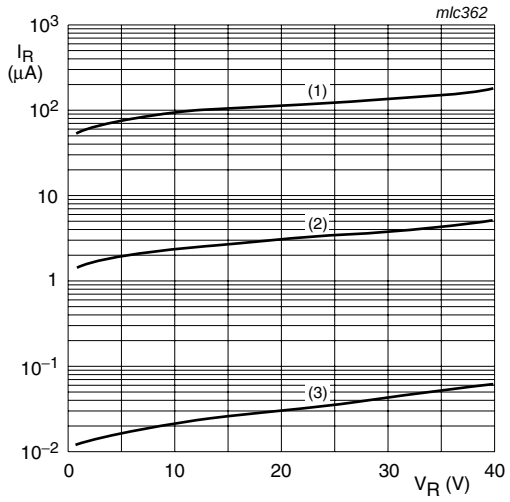
[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.

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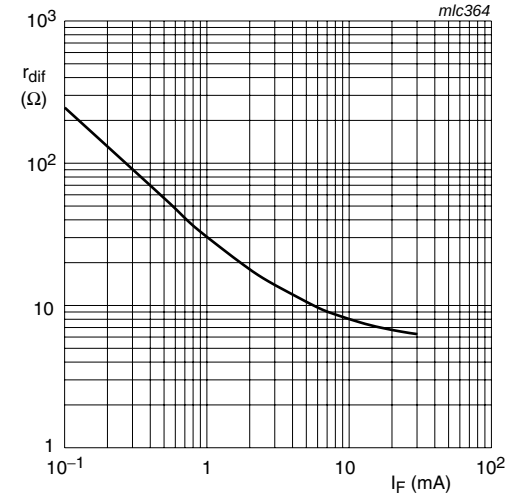
(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C
(4) T_{amb} = −40 °C

Fig 1. Forward current as a function of forward voltage; typical values



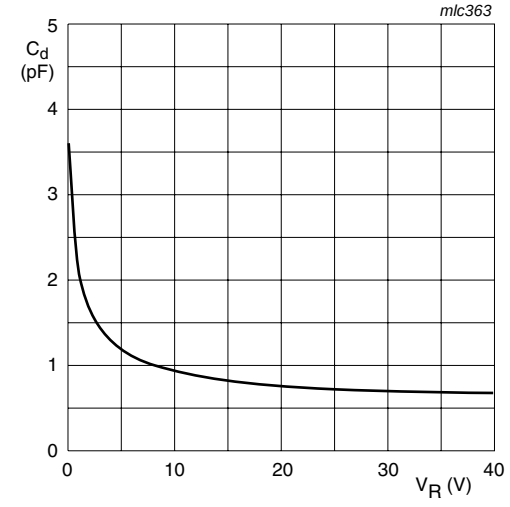
(1) T_{amb} = 125 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C

Fig 2. Reverse current as a function of reverse voltage; typical values



f = 10 kHz

Fig 3. Differential resistance as a function of forward current; typical values



T_{amb} = 25 °C; f = 1 MHz

Fig 4. Diode capacitance as a function of reverse voltage; typical values

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8. Package outline

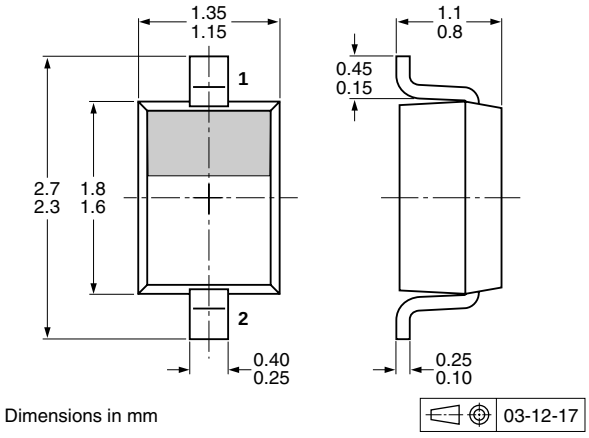


Fig 5. Package outline SOD323 (SC-76)

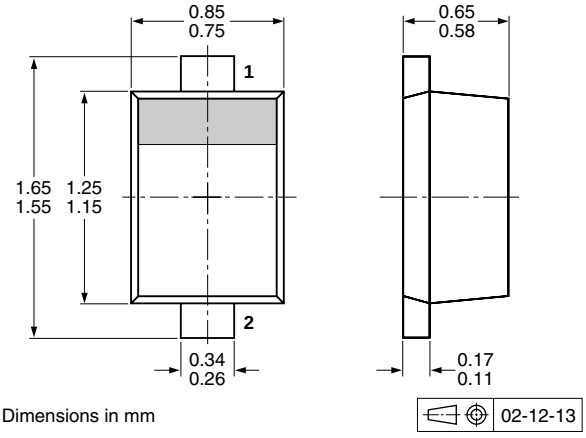


Fig 6. Package outline SOD523 (SC-79)

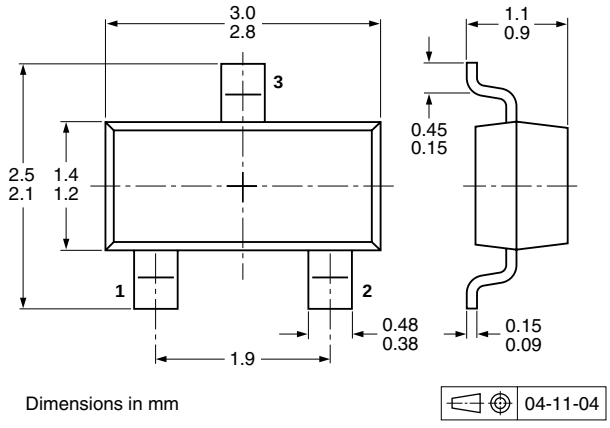


Fig 7. Package outline SOT23 (TO-236AB)

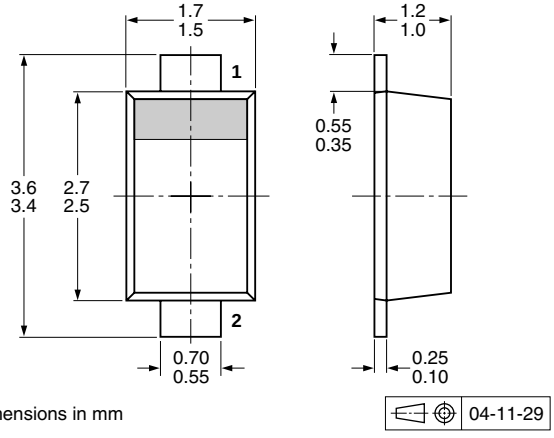


Fig 8. Package outline SOD123F

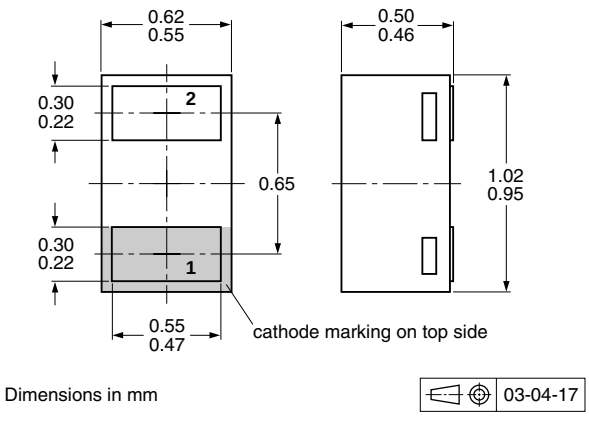


Fig 9. Package outline SOD882

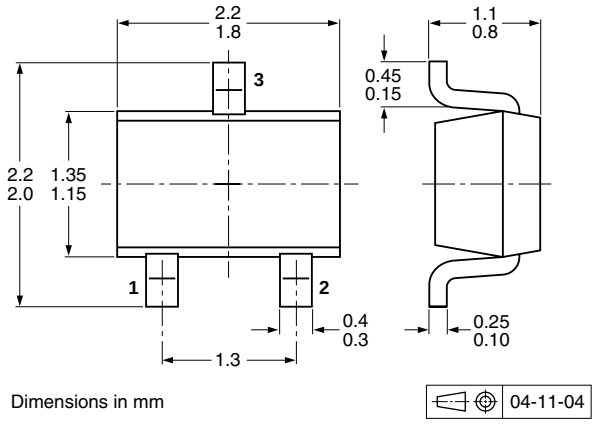


Fig 10. Package outline SOT323 (SC-70)

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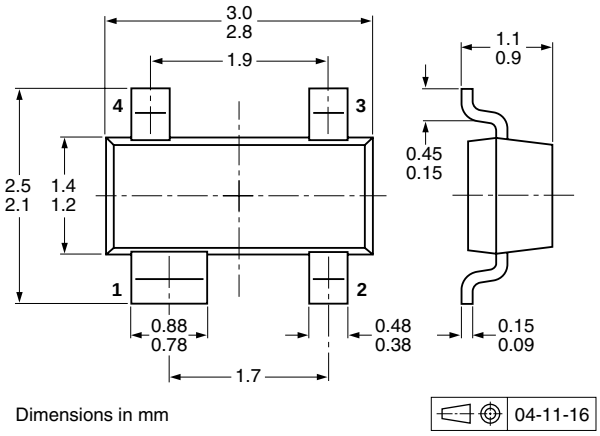


Fig 11. Package outline SOT143B

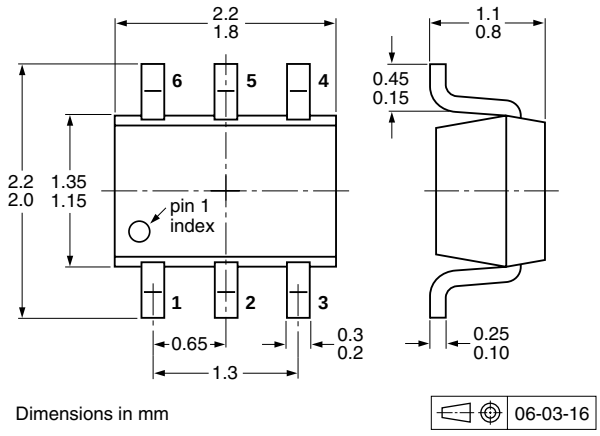


Fig 12. Package outline SOT363 (SC-88)

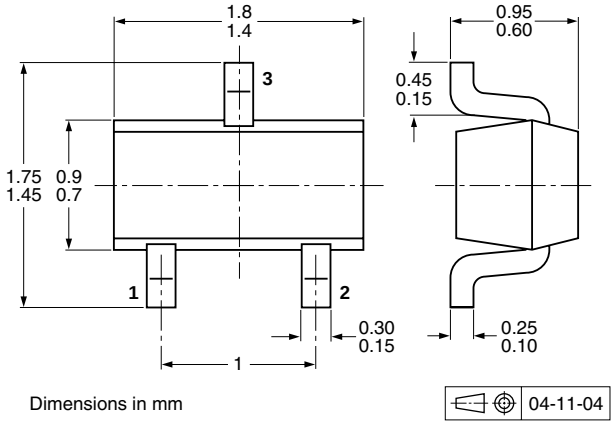


Fig 13. Package outline SOT416 (SC-75)

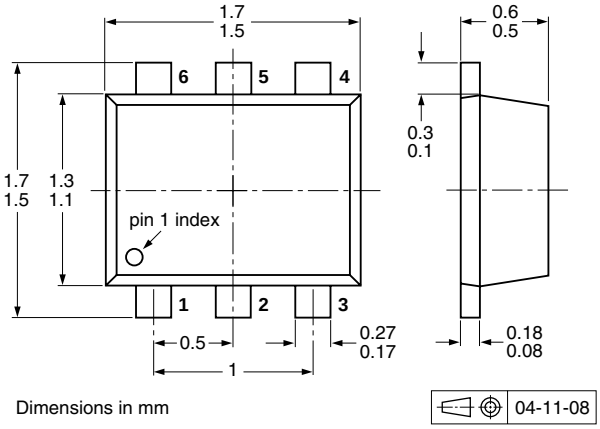


Fig 14. Package outline SOT666

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9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description		Packing quantity			
				3000	4000	8000	10000
1PS70SB40	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
1PS76SB40	SOD323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
1PS79SB40	SOD523	2 mm pitch, 8 mm tape and reel		-	-	-315	-
		4 mm pitch, 8 mm tape and reel		-115	-	-	-135
BAS40	SOT23	4 mm pitch, 8 mm tape and reel		-215	-	-	-235
BAS40H	SOD123F	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
BAS40L	SOD882	2 mm pitch, 8 mm tape and reel		-	-	-	-315
BAS40W	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
1PS70SB44	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
BAS40-04	SOT23	4 mm pitch, 8 mm tape and reel		-215	-	-	-235
BAS40-04W	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
1PS70SB45	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
1PS75SB45	SOT416	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
BAS40-05	SOT23	4 mm pitch, 8 mm tape and reel		-215	-	-	-235
BAS40-05W	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
1PS70SB46	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
BAS40-06	SOT23	4 mm pitch, 8 mm tape and reel		-215	-	-	-235
BAS40-06W	SOT323	4 mm pitch, 8 mm tape and reel		-115	-	-	-135
BAS40-07	SOT143B	4 mm pitch, 8 mm tape and reel		-215	-	-	-235
BAS40-07V	SOT666	2 mm pitch, 8 mm tape and reel		-	-	-315	-
		4 mm pitch, 8 mm tape and reel		-	-115	-	-
BAS40-05V	SOT666	2 mm pitch, 8 mm tape and reel		-	-	-315	-
		4 mm pitch, 8 mm tape and reel		-	-115	-	-
1PS88SB48	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-	-	-165
BAS40XY	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-	-	-165

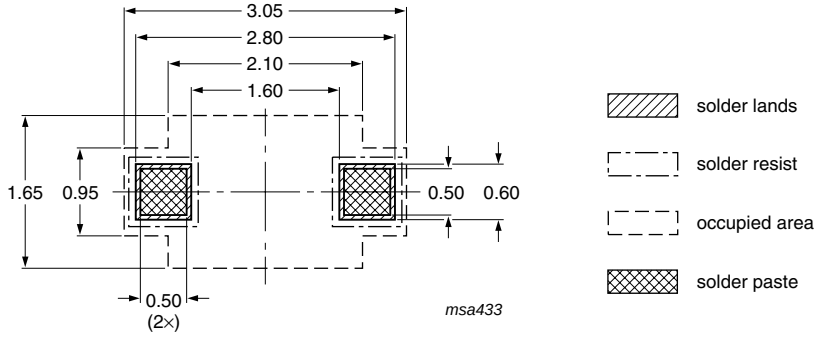
[1] For further information and the availability of packing methods, see Section 13.

[2] T1: normal taping

[3] T2: reverse taping

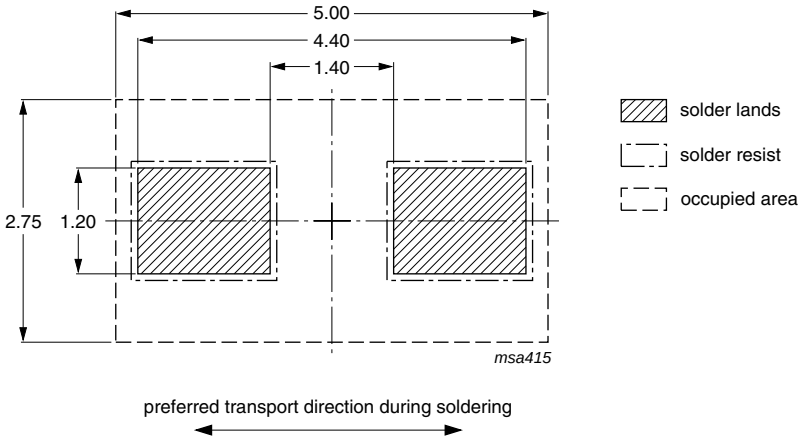
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10. Soldering



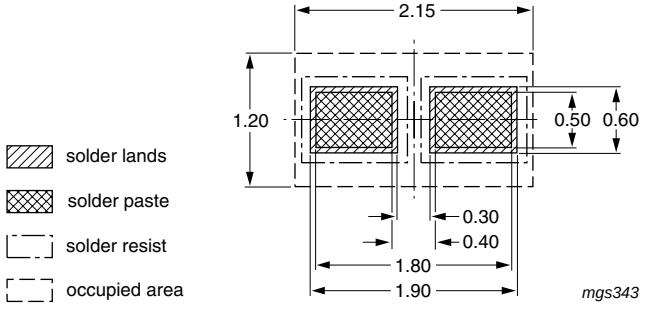
Dimensions in mm

Fig 15. Reflow soldering footprint SOD323 (SC-76)



Dimensions in mm

Fig 16. Wave soldering footprint SOD323 (SC-76)

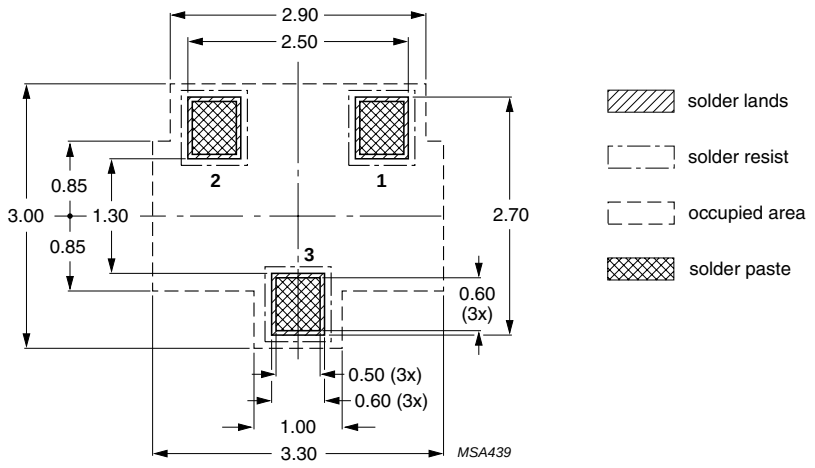


Reflow soldering is the only recommended soldering method.

Dimensions in mm

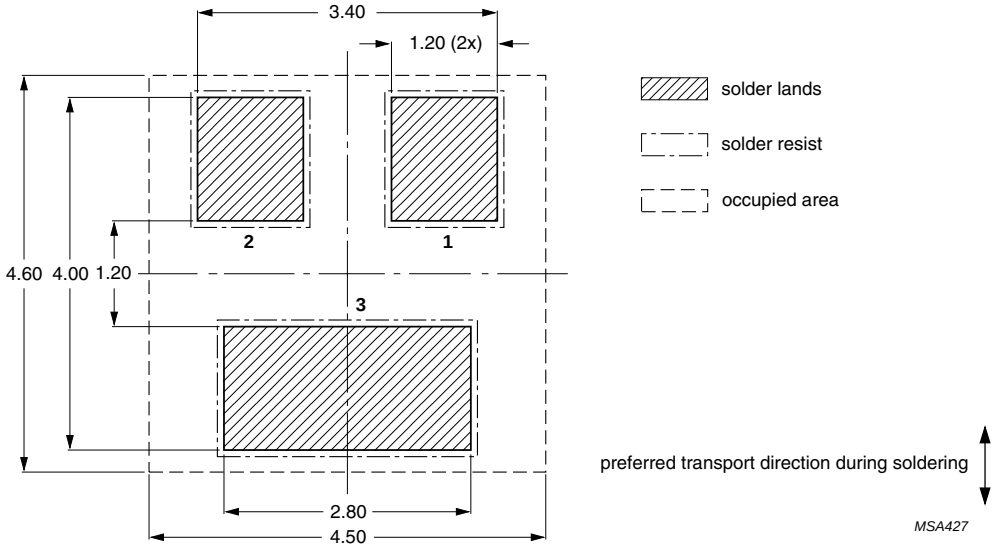
Fig 17. Reflow soldering footprint SOD523 (SC-79)

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Dimensions in mm

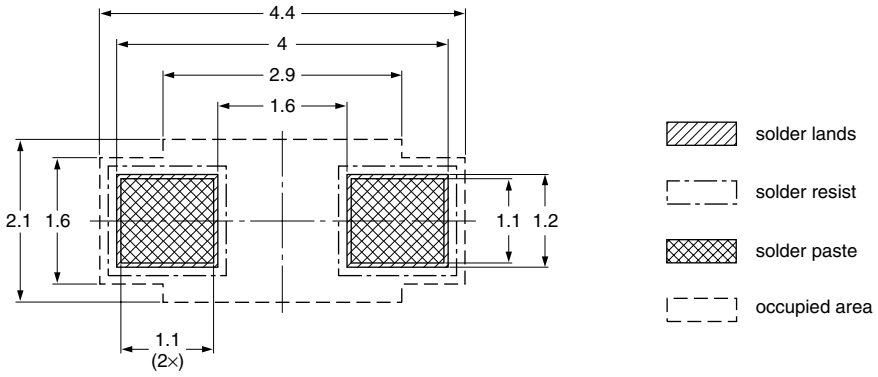
Fig 18. Reflow soldering footprint SOT23 (TO-236AB)



Dimensions in mm

Fig 19. Wave soldering footprint SOT23 (TO-236AB)

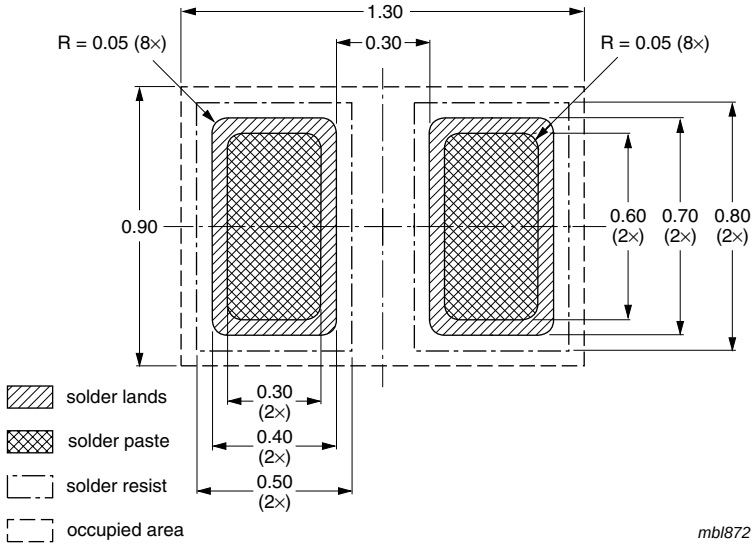
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Reflow soldering is the only recommended soldering method.

Dimensions in mm

Fig 20. Reflow soldering footprint SOD123F



Reflow soldering is the only recommended soldering method.

Dimensions in mm

Fig 21. Reflow soldering footprint SOD882

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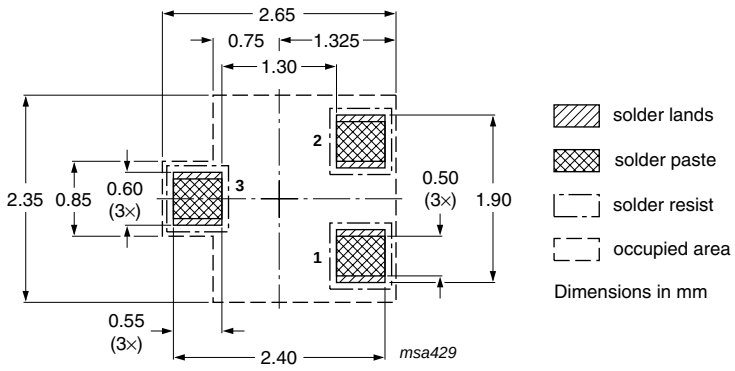


Fig 22. Reflow soldering footprint SOT323 (SC-70)

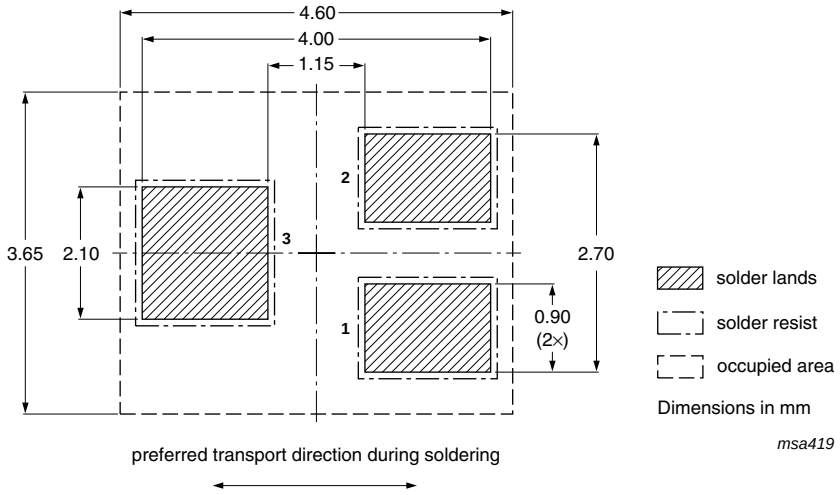
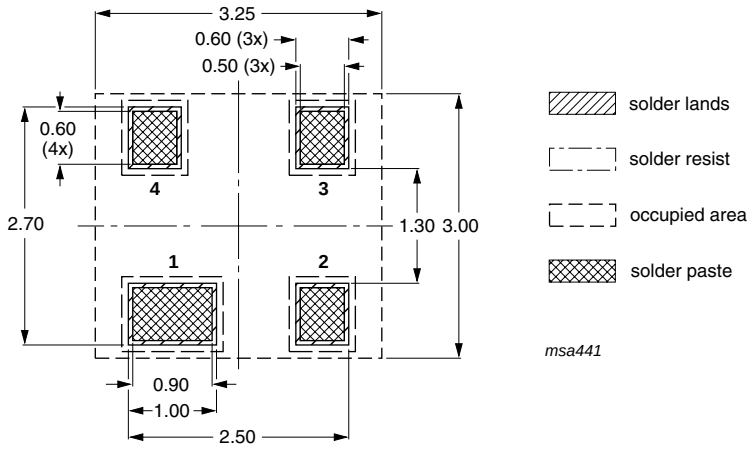


Fig 23. Wave soldering footprint SOT323 (SC-70)

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Dimensions in mm

Fig 24. Reflow soldering footprint SOT143B

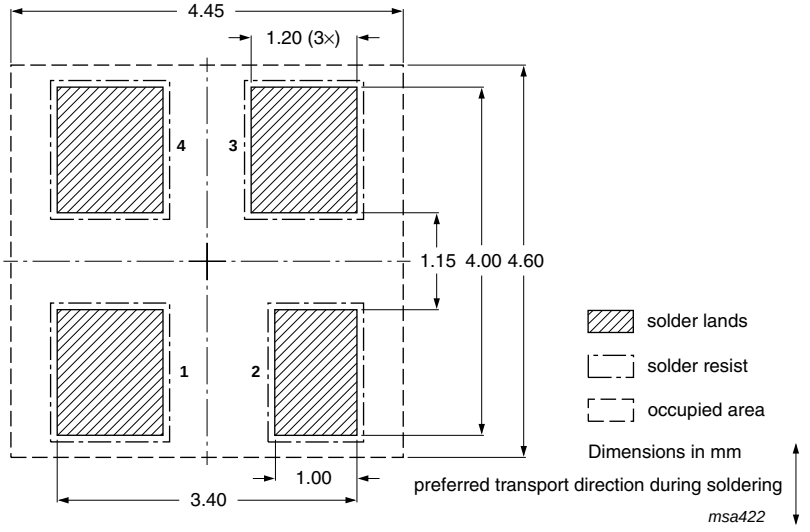


Fig 25. Wave soldering footprint SOT143B

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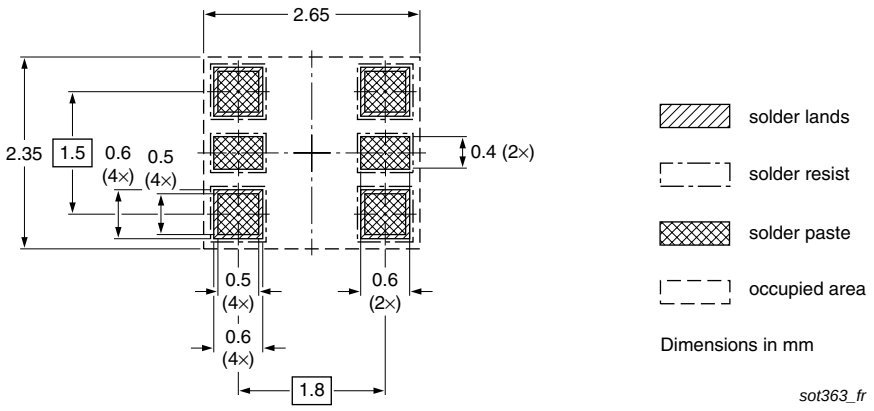


Fig 26. Reflow soldering footprint SOT363 (SC-88)

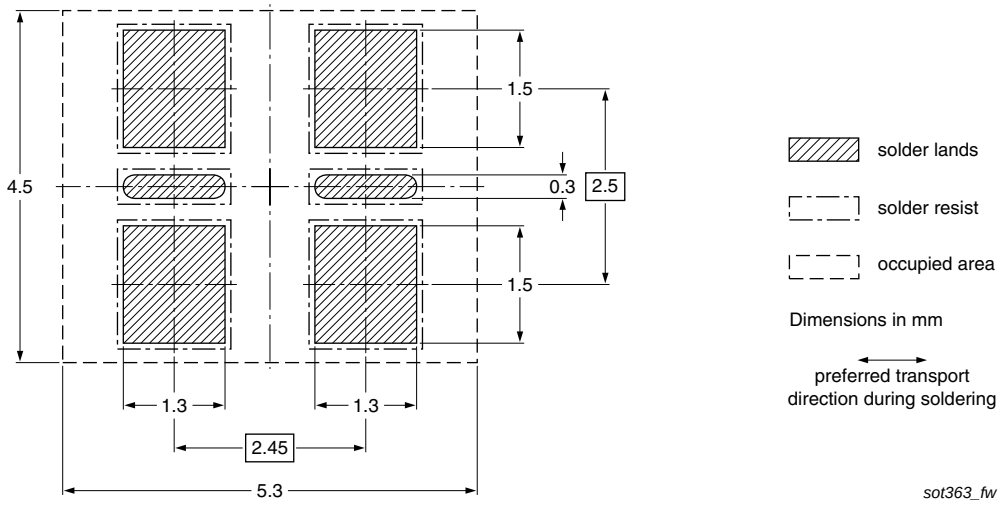


Fig 27. Wave soldering footprint SOT363 (SC-88)

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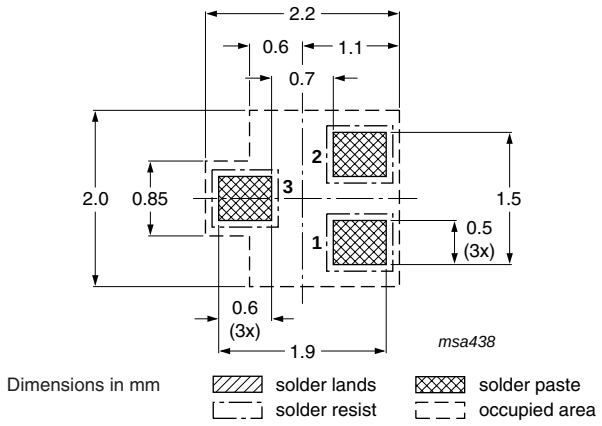
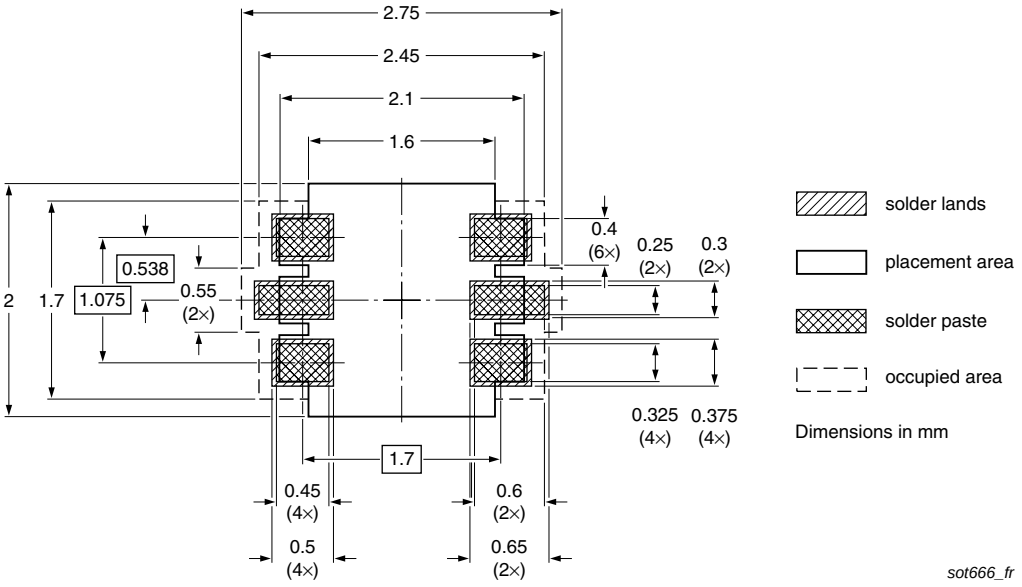


Fig 28. Reflow soldering footprint SOT416



Reflow soldering is the only recommended soldering method.

Fig 29. Reflow soldering footprint SOT666

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11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS40_1PSXXSB4X_SER_8	20100113	Product data sheet	-	BAS40_1PSXXSB4X_SER_7
Modifications:	• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Figure 12 “Package outline SOT363 (SC-88)”: updated • Figure 16 “Wave soldering footprint SOD323 (SC-76)”: updated • Figure 17 “Reflow soldering footprint SOD523 (SC-79)”: updated • Figure 21 “Reflow soldering footprint SOD882”: updated • Figure 22 “Reflow soldering footprint SOT323 (SC-70)”: updated • Figure 23 “Wave soldering footprint SOT323 (SC-70)”: updated • Figure 25 “Wave soldering footprint SOT143B”: updated • Figure 26 “Reflow soldering footprint SOT363 (SC-88)”: updated • Figure 27 “Wave soldering footprint SOT363 (SC-88)”: updated • Figure 28 “Reflow soldering footprint SOT416”: updated • Figure 29 “Reflow soldering footprint SOT666”: updated			
BAS40_1PSXXSB4X_SER_7	20060512	Product data sheet	-	BAS40_1PSXXSB4X_SER_6
BAS40_1PSXXSB4X_SER_6	20050809	Product data sheet	-	1PS70SB40_3 1PS75SB45_2 1PS76SB40_3 1PS79SB40_2 1PS88SB48_3 BAS40H_1 BAS40L_1 BAS40-05V_1 BAS40-07V_1 BAS40W_3 BAS40_SERIES_5
1PS70SB40_3	19990426	Product specification	-	1PS70SB40_2
1PS75SB45_2	19990426	Product specification	-	1PS75SB45_1
1PS76SB40_3	20040126	Product specification	-	1PS76SB40_2
1PS79SB40_2	19990426	Product specification	-	1PS79SB40_1
1PS88SB48_3	20021107	Product specification	-	1PS88SB48_2
BAS40H_1	20050425	Product data sheet	-	-
BAS40L_1	20030520	Product specification	-	-
BAS40-05V_1	20021121	Product specification	-	-
BAS40-07V_1	20020327	Product specification	-	-
BAS40W_3	19990426	Product specification	-	BAS40W_2
BAS40_SERIES_5	20011010	Product specification	-	BAS40_4

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12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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